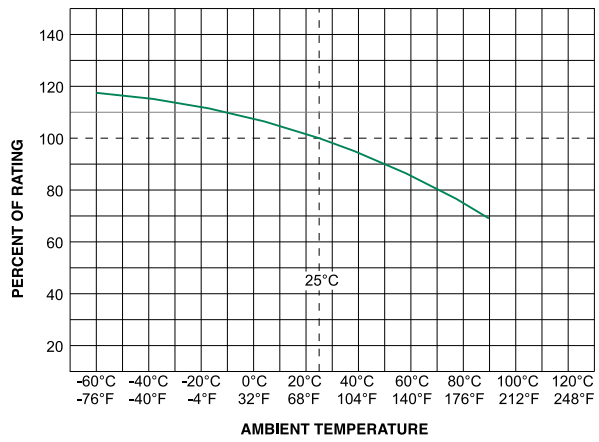
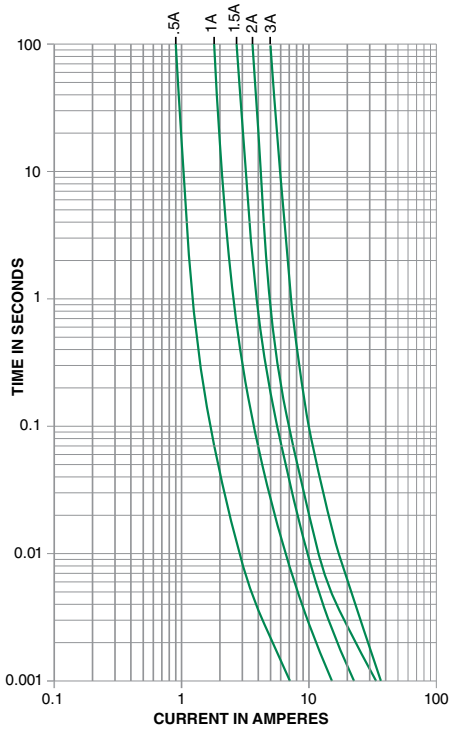
Temperature Rerating Curve

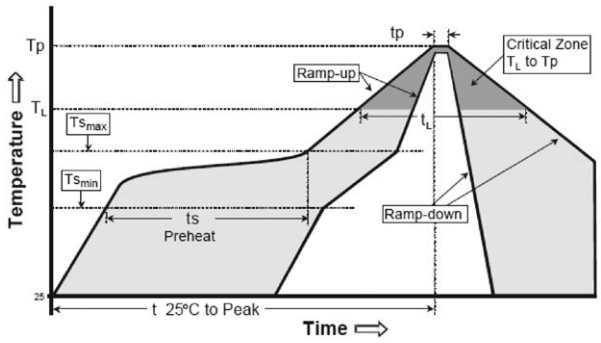


Average Time Current Curves



Soldering Parameters - Wave Soldering

Reflow Condition		Pb – Free assembly
Pre Heat	-Temperature Min ($T_{s(min)}$)	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	-Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		$250^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C

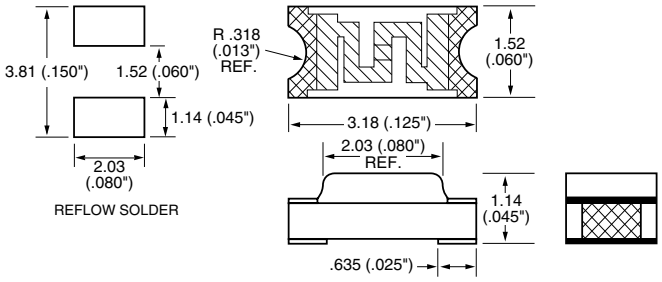


Product Characteristics

Materials	**Body:** Epoxy Substrate **Terminations:** 95% Tin / 5% Lead over Nickel over Copper **Element Cover Coat:** Conformal Coating
Operating Temperature	– 55°C to 90°C. Consult temperature rerating curve chart. For operation above 90°C contact Littelfuse.
Humidity	MIL-STD-202F Method 103B Condition D
Thermal Shock	Withstands 5 cycles of – 55°C to 125°C

Vibration	Withstands 10-55 Hz per MIL-STD-202F, Method 201A and 10-2000 Hz at 20 G's per MIL-STD-202F, Method 204D, Condition D
Insulation Resistance (After Opening)	Greater than 10,000 ohms
Resistance to Soldering Heat	Withstands 60 seconds above 200°C and up to 260°C, maximum

Dimensions



Part Marking System

Amp Code	Marking Code
.500	**F**
001.	**H**
01.5	**K**
002.	**N**
003.	**P**

Part Numbering System

0430 .500 WR

- **SERIES**
- **AMP CODE**
- **QUANTITY CODE**

Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
8mm Tape and Reel	EIA RS-481-2 (IEC 286, part 3)	3000	WR